



P96/P26 Polyimide-based Prepreg and Laminate

Isola offers a product line of polyimide-based prepreg (**P26**) and core material (**P96**) for high temperature printed circuit applications. These products consist of a flame resistant, polyimide resin system suitable for military, commercial or industrial electronic applications requiring superior performance and the utmost in thermal properties. These products utilize a polyimide and thermoplastic blend resin, fully cured without the use of MDA (Methylenedianiline). This results in a polymer with a high Tg without the characteristic difficulties of brittleness and low initial bond strength associated with traditional thermoset polyimides.

www.isola-group.com/products/P96

ORDERING INFORMATION:

Contact your local sales representative or visit www.isola-group.com for further information.

Isola Group
3100 West Ray Road
Suite 301
Chandler, AZ 85226
Phone: 480-893-6527
Fax: 480-893-1409
info@isola-group.com

Isola Asia Pacific (Hong Kong) Ltd.
Unit 3512 - 3522, 35/F
No. 1 Hung To Road, Kwun Tong,
Kowloon, Hong Kong
Phone: 852-2418-1318
Fax: 852-2418-1533
info.hkg@isola-group.com

Isola GmbH
Isola Strasse 2
D-52348 Düren, Germany
Phone: 49-2421-8080
Fax: 49-2421-808164
info-dur@isola-group.com

High Performance

P96/P26 Data Sheet

Tg 260, Td 396
Dk 3.76, Df 0.017
/40 /41

Features

- High Thermal Performance
 - ▶ Tg: 260°C (TMA)
 - ▶ Greater thermal performance over epoxy-bismaleimide blends
- T260: 60 minutes
- T288: 60 minutes
- RoHS Compliant
- Maintains Bond Strength at High Temperature
- Tough Resin System
 - ▶ Improved processing due to less brittleness
 - ▶ Less delamination from machining
- Brominated Chemistry, Thermally Stable Laminate System
 - ▶ Full benefits of 100% polyimide performance
- Non-MDA (Methylenedianiline) Chemistry
 - ▶ Meets all OSHA 1910.1050 requirements
- Core Material Standard Availability
 - ▶ Thickness: 0.002" (0.05 mm) to 0.125" (3.2 mm)
 - ▶ Available in full size sheet or panel form
- Prepreg Standard Availability
 - ▶ Roll or panel form
 - ▶ Tooling of prepreg panels available
- Copper Foil Type Availability
 - ▶ Standard HTE Grade 3
 - ▶ RTF (Reverse Treat Foil)
- Copper Weights
 - ▶ ½, 1 and 2 oz (18, 35 and 70 µm) available
 - ▶ Heavier copper available upon request
 - ▶ Thinner copper foil available upon request
- Glass Fabric Availability
 - ▶ Standard E-glass
- Industry Approvals
 - ▶ IPC-4101D WAM1 /40 /41
 - ▶ UL - File Number E41625

P96/P26 Typical Values

Property		Typical Values		
		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		260	°C	2.4.25
Decomposition Temperature (Td) by TGA @ 5% weight loss		396	°C	ASTM D3850
T260		60	Minutes	ASTM D3850
T288		60	Minutes	ASTM D3850
CTE, Z-axis	A. Pre-Tg	55	ppm/°C	2.4.24
	B. Post-Tg			
CTE, X-, Y-axes	A. Pre-Tg	13/14	ppm/°C	2.4.24
	B. Post-Tg	14/17		
Z-axis Expansion (50-260°C)		1.5	%	2.4.24
Thermal Conductivity		0.4	W/mK	ASTM D5930
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched	Pass	Rating	2.4.13.1
	B. Etched			
Dk, Permittivity (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz	3.83	-	2.5.5.9
	B. @ 500 MHz	3.80		2.5.5.9
	C. @ 1 GHz	3.78		2.5.5.9
	D. @ 2 GHz	3.76		Bereskin Stripline
	E. @ 5 GHz	3.73		Bereskin Stripline
	F. @ 10 GHz	3.73		Bereskin Stripline
Df, Loss Tangent (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz	0.0135	-	2.5.5.9
	B. @ 500 MHz	0.0151		2.5.5.9
	C. @ 1 GHz	0.0172		2.5.5.9
	D. @ 2 GHz	0.0179		Bereskin Stripline
	E. @ 5 GHz	0.0188		Bereskin Stripline
	F. @ 10 GHz	0.021		Bereskin Stripline
Volume Resistivity	A. 96/35/90	-	MΩ-cm	2.5.17.1
	B. After moisture resistance	3.0x10 ⁸		
	C. At elevated temperature	7.0x10 ⁸		
Surface Resistivity	A. 96/35/90	-	MΩ	2.5.17.1
	B. After moisture resistance	3.0x10 ⁶		
	C. At elevated temperature	2.0x10 ⁸		
Dielectric Breakdown		>55	kV	2.5.6
Arc Resistance		130	Seconds	2.5.1
Electric Strength (Laminate & prepreg as laminated)		44 (1100)	kV/mm (V/mil)	2.5.6.2
Comparative Tracking Index (CTI)		4 (100-174)	Class (Volts)	UL-746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile – all copper weights >17 microns	1.14 (6.5)	N/mm (lb/inch)	2.4.8
	B. Standard profile copper	-		2.4.8.2
	1. After thermal stress	1.25 (7.0)		2.4.8.3
	2. At 125°C (257°F)	1.25 (7.0)		-
	3. After process solutions	1.14 (6.5)	-	
Flexural Strength	A. Lengthwise direction	83,600	lb/inch ²	2.4.4
	B. Crosswise direction	55,500		
Tensile Strength	A. Lengthwise direction	55,000	lb/inch ²	-
	B. Crosswise direction	35,370		
Young's Modulus	A. Grain direction	3958	ksi	ASTM D790-15e2
	B. Fill direction	3530		
Poisson's Ratio	A. Grain direction	0.189	-	ASTM D3039-95a
	B. Fill direction	0.154		
Moisture Absorption		0.5	%	2.6.2.1
Flammability (Laminate & prepreg as laminated)		V-0	Rating	UL 94
Max Operating Temperature		140	°C	-

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

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